



PK110 (v1.3.2) January 16, 2012

100% Material Declaration Data Sheet for FGG484 Package

Average Weight: 1.9500 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.049000	2.540
	Silicon	7440-21-3	100.00		0.049000	
Die Attach Material					0.007900	0.410
	Polymetric Resin	Trade Secret	3.00		0.000200	
	Diester Resin	Trade Secret	20.00		0.001500	
	Acrylate resin	Trade Secret	7.00		0.000600	
	Silver	7440-22-4	70.00		0.005600	
Mold Compound					0.001750	0.090
	SiO2 Filler	60676-86-0	86.20		0.001510	
	Epoxy Resin A	Trade Secret	3.00		0.000050	
	Epoxy Resin B	Trade Secret	3.00		0.000050	
	Phenol Resin A	Trade Secret	3.00		0.000050	
	Phenol Resin B	Trade Secret	3.00		0.000050	
	Metal Hydroxide	Trade Secret	1.50		0.000030	
	Carbon black	1333-86-4	0.30		0.000010	
Gold Wire					0.015870	0.810
	Gold (Au)	7440-57-5	100.00		0.015870	
Solder Balls					0.404300	20.730
	Tin (Sn)	7440-31-5	95.50		0.386100	
	Silver (Ag)	7440-22-4	4.00		0.016800	
	Copper (Cu)	7440-50-8	0.50		0.002000	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					1.470700	75.420
	Copper (Cu)	7440-50-8	46.27		0.680500	
	Gold (Au)	7440-57-5	0.13		0.001900	
	Nickel (Ni)	7440-02-0	0.60		0.008800	
	Glass Fiber	N/A	23.00		0.338300	
	Halogen Fire Retardant	13776-74-4, 7631-86-9	3.20		0.047100	
	BT (core)	N/A	16.80		0.247100	
	Solder mask	N/A	10.00		0.147000	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/21/06	1.0	Initial Xilinx release.
05/15/06	1.1	100% Material Declaration
09/18/06	1.2	Updated component descriptions.
01/08/07	1.2.1	Corrected Gold Wire CAS number entry.
05/30/08	1.3	Correct CAS number for silver in solder ball composition. Updated Weights.
12/12/08	1.3.1	Tech Pubs' edit.
01/16/12	1.3.2	Tech Pubs' edit.

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